

Single N-Channel MOSFET

DESCRIPTION

SMC3910J is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior, fast switching performance, and withstand high energy pulse in the avalanche and commutation mode.

PART NUMBER INFORMATION

SMC 3910 J - TR G
 a b c d e

- a : Company name.
- b : Product Serial number.
- c : Package code J:SOT-223
- d : Handling code TR:Tape&Reel
- e : Green produce code G:RoHS Compliant

FEATURES

$V_{DS} = 100V, I_D = 3A$

$R_{DS(ON)} = 165m\Omega(Typ.) @ V_{GS} = 10V$
 $R_{DS(ON)} = 170m\Omega(Typ.) @ V_{GS} = 4.5V$

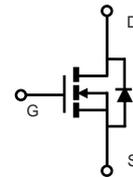
- ◆ 100% EAS Guaranteed
- ◆ Improved dv/dt capability
- ◆ Fast switching

APPLICATIONS

- ◆ LED applications
- ◆ Transformer Driving Switch
- ◆ Load Switch



SOT-223



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	100	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	3
		$T_A = 70^\circ C$	2.4
I_{DM}	Pulsed Drain Current ^A	12	A
I_{AS}	Avalanche Current ^A	5	A
EAS	Single Pulse Avalanche energy $L=0.3mH$ ^{AF}	3.75	mJ
P_D	Power Dissipation ^C	$T_A = 25^\circ C$	3.6
		$T_A = 70^\circ C$	2.3
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^B	$t \leq 10s$	35	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^{BD}	Steady-State	70	
$R_{\theta JC}$	Thermal Resistance Junction to Case		35	

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

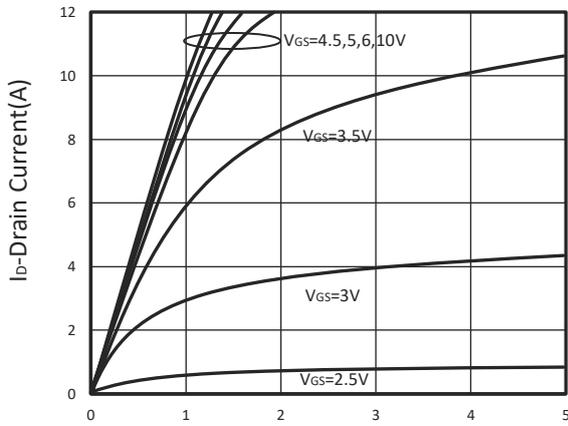
Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	30			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250 μ A	1.2	1.8	2.5	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} = \pm 20V			\pm 100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V, T _J =25 $^\circ$ C			1	μ A
		V _{DS} =24V, V _{GS} =0V, T _J =75 $^\circ$ C			10	
R _{DS(ON)}	Drain-source On-Resistance ^E	V _{GS} =10V, I _D =3A V _{GS} =4.5V, I _D =2A		165 170	180 190	m Ω
G _{fs}	Forward Transconductance	V _{DS} =10V, I _D =1A		5		S
Diode Characteristics						
V _{SD}	Diode Forward Voltage ^E	I _S =1A, V _{GS} =0V		0.7	1	V
I _S	Diode Continuous Forward Current				3	A
T _{rr}	Reverse Recovery Time	I _S =3A, di/dt=100A/ μ s		25		ns
Q _{rr}	Reverse Recovery Charge				30	
Dynamic and Switching Parameters						
Q _g	Total Gate Charge	V _{DS} =30V, V _{GS} =10V, I _D =3A		11.3	16.9	nC
Q _g	Total Gate Charge (4.5V)			5.5	11	
Q _{gs}	Gate-Source Charge			2	3	
Q _{gd}	Gate-Drain Charge			2.1	4.2	
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz		470		pF
C _{oss}	Output Capacitance			38		
C _{rss}	Reverse Transfer Capacitance			21		
t _{d(on)}	Turn-On Time ^E	V _{DD} =30V, V _{GEN} =10V, R _G =6 Ω , I _D =1A		9	17	ns
t _r				6.3	12	
t _{d(off)}	Turn-Off Time ^E			18	34	
t _f				4.2	8	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

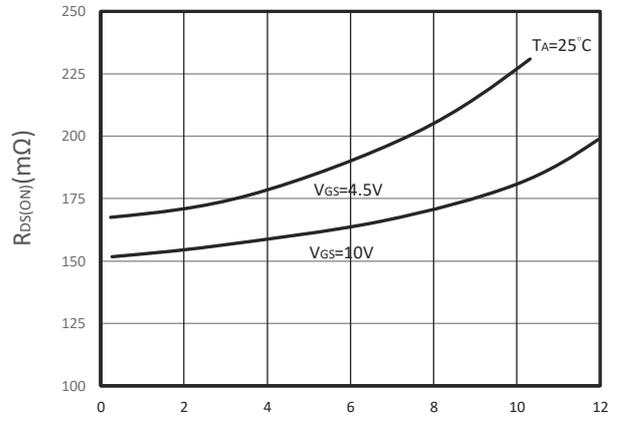
- A. Pulsed width limited by maximum junction temperature, T_{J(MAX)}=150 $^\circ$ C.
- B. Measure the value in a still air environment at T_A=25 $^\circ$ C, using an installation mounted on a 1 in2 FR-4 board, maximum junction temperature T_{J(MAX)}=150 $^\circ$ C.
- C. Using junction-to-case thermal resistance, dissipation limit in the case of additional heat.
- D. T_{J(MAX)}=150 $^\circ$ C, using junction-to-case thermal resistance (R_{θJC}) is more useful in additional heat sinking is used.
- E. The pulse test width is \leq 300 μ s and the duty cycle \leq 2%.
- F. The EAs data shows Maximum, tested and pulse width limited by maximum.

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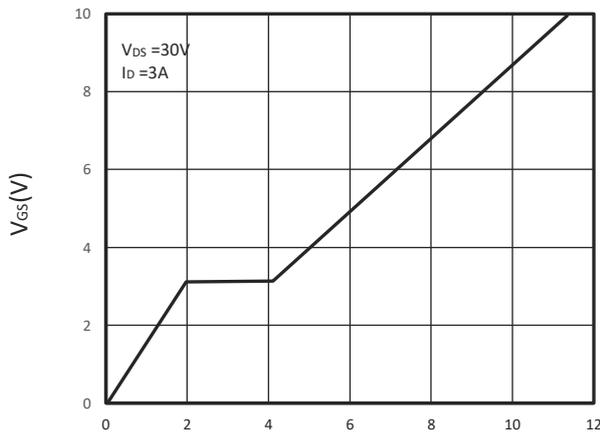
TYPICAL CHARACTERISTICS



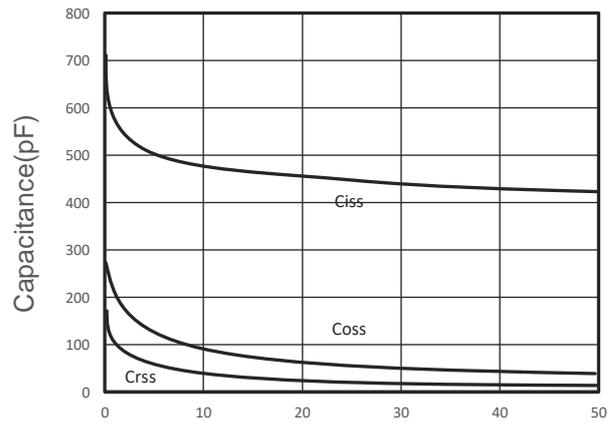
V_{DS}-Drain Source Voltage (V)
Output Characteristics



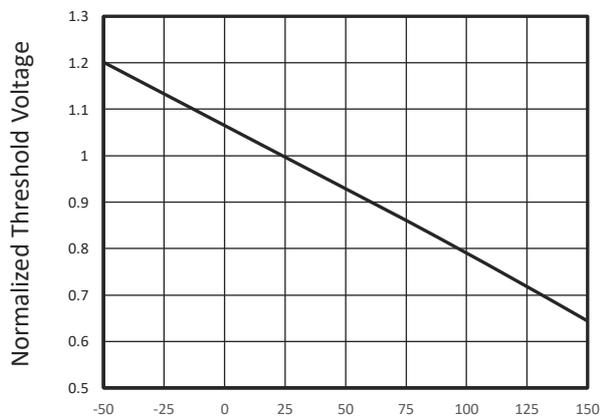
Id-Drain Current (A)
Drain-Source On Resistance



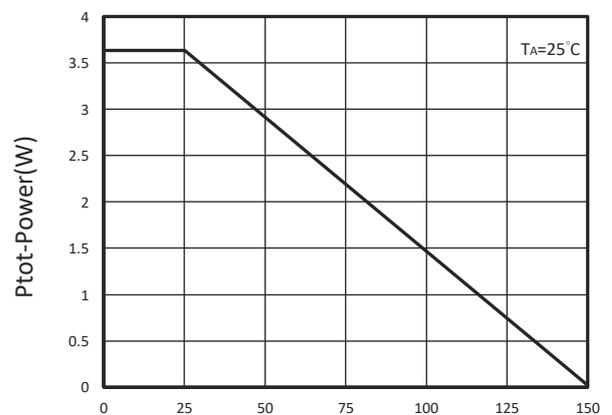
Qg-Gate Charge (nC)
Gate Charge



V_{DS}-Drain Source Voltage (V)
Capacitance

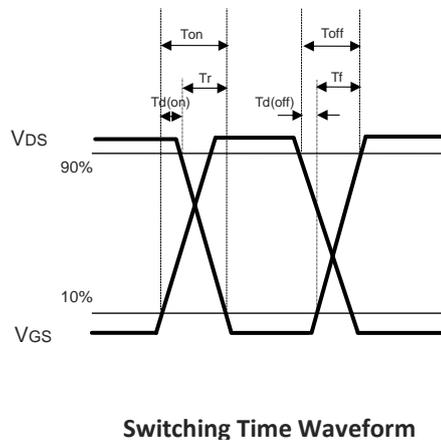
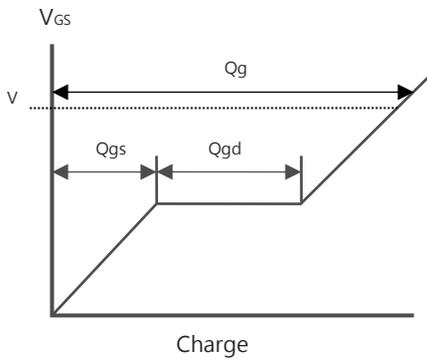
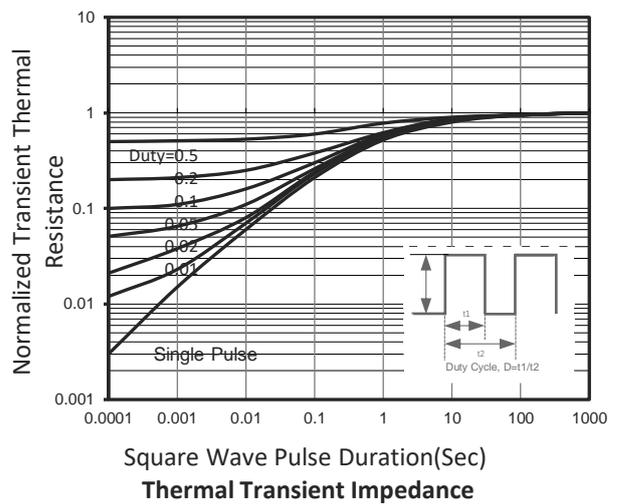
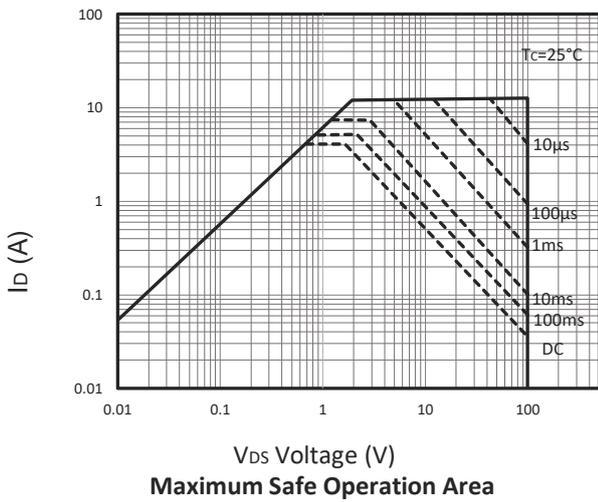
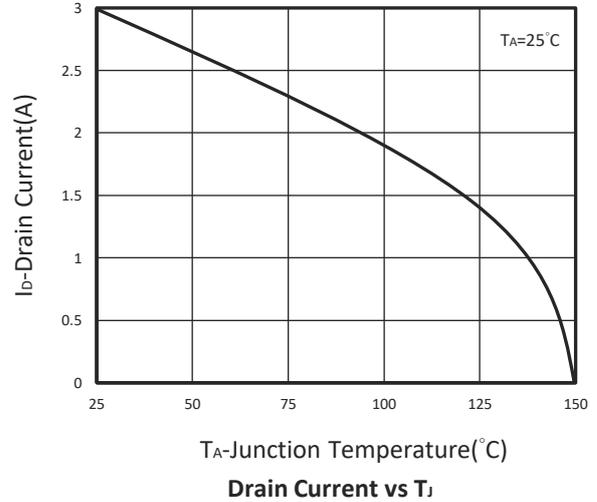
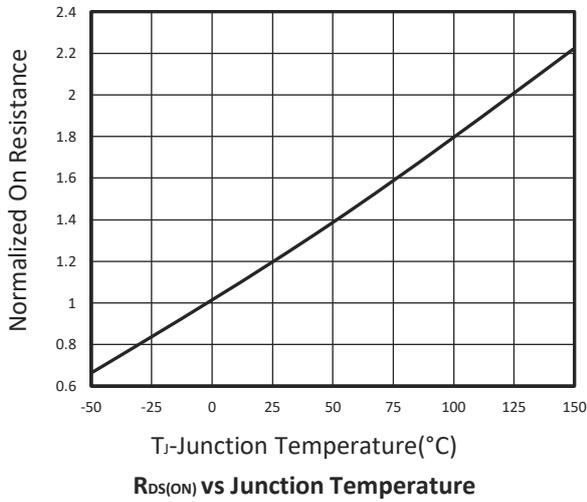


T_J-Junction Temperature (°C)
Gate Threshold Voltage

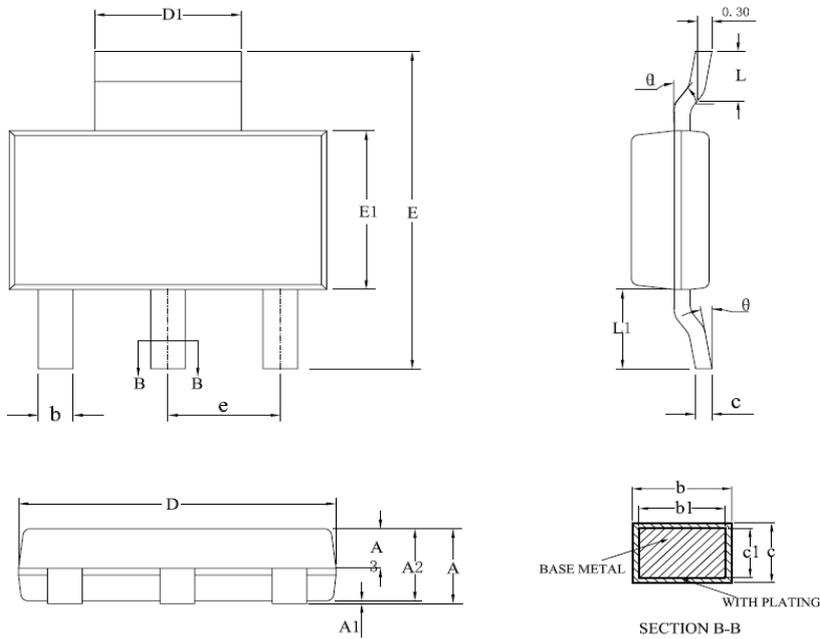


T_J-Junction Temperature (°C)
Power Dissipation

TYPICAL CHARACTERISTICS



■ SOT-223 PACKAGE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
A3	0.800	1.000	0.031	0.039
b	0.660	0.820	0.026	0.032
b1	0.680	0.740	0.027	0.029
c	0.300	0.350	0.012	0.014
c1	0.290	0.310	0.011	0.012
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	6.830	7.070	0.269	0.278
E1	3.300	3.700	0.130	0.146
e	2.300 BSC.		0.091 BSC.	
L	0.900	1.150	0.035	0.045
L1	1.75 BSC.		0.069 BSC.	
θ	0°	10°	0°	10°